

LNPTTM THERMOCOMPTM COMPOUND EC005

EC-1005

REGION EUROPE

DESCRIPTION

LNP THERMOCOMP EC005 compound is based on Polyetherimide (PEI) resin containing 25% carbon fiber. Added features of this grade include: Electrically Conductive.

GENERAL INFORMATION

Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Injection Molding

INDUSTRY

Automotive
Building and Construction
Consumer
Electrical and Electronics
Industrial

SUB INDUSTRY

Aerospace
Building Component
Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Mobile Phone - Computer - Tablets
Electrical

TYPICAL PROPERTY VALUES

Revision 20230607

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	200	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.3	%	ISO 527
Tensile Modulus, 1 mm/min	18400	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	243	MPa	ISO 178
Flexural Modulus, 2 mm/min	13600	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched 80*10*4 +23°C	35	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	214	°C	ISO 75 /Af
PHYSICAL ⁽¹⁾			
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1 – 0.3	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.3 – 0.5	%	ISO 294
Density	1.37	g/cm ³	ISO 1183
ELECTRICAL ⁽¹⁾			
Surface Resistivity	1.E+02 – 1.E+04	Ω	ASTM D257
INJECTION MOLDING ⁽³⁾			

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	360 – 400	°C	
Rear - Zone 1 Temperature	360 – 380	°C	
Middle - Zone 2 Temperature	370 – 390	°C	
Front - Zone 3 Temperature	380 – 400	°C	
Nozzle Temperature	390 – 400	°C	
Mold Temperature	140 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw speed (Circumferential speed)	0.2 – 0.3	m /s	
Vent Depth	0.025 – 0.076	mm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

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